



# PRODUCT/PROCESS CHANGE NOTIFICATION

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PCN APM-SLI/09/4408  
Notification Date 03/12/2009

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**DIE REDESIGN FOR ST3232xx and ST3222xx PRODUCT FAMILIES**  
**(except the High ESD version)**

**Table 1. Change Implementation Schedule**

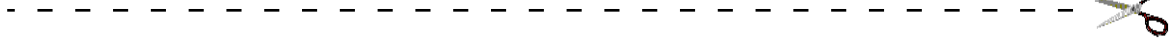
Forecasted implementation date for change	09-Jun-2009
Forecasted availability date of samples for customer	05-Mar-2009
Forecasted date for <b>STMicroelectronics</b> change Qualification Plan results availability	05-Mar-2009
Estimated date of changed product first shipment	11-Jun-2009

**Table 2. Change Identification**

Product Identification (Product Family/Commercial Product)	see attached list
Type of change	Waferfab process change
Reason for change	To improve Service
Description of the change	Following Divisional commitment towards a continuous improvement philosophy, a new die for the ST3232xx and ST3222xx families (except the High ESD version) has been redesigned. Diffusion, assembly and testing location are maintained. No process change. Samples of ST3232CDR are already available. Other samples versions of ST3232xx family will be available on week 12 and samples of ST3222xx family will be available on week 22.
Product Line(s) and/or Part Number(s)	See attached
Description of the Qualification Plan	See attached
Change Product Identification	Identification will be ensured by the Q.A. number.
Manufacturing Location(s)	

**Table 3. List of Attachments**

Customer Part numbers list	
Qualification Plan results	



Customer Acknowledgement of Receipt		<b>PCN APM-SLI/09/4408</b>					
Please sign and return to STMicroelectronics Sales Office		<b>Notification Date 03/12/2009</b>					
<input type="checkbox"/> Qualification Plan Denied <input type="checkbox"/> Qualification Plan Approved  <input type="checkbox"/> Change Denied <input type="checkbox"/> Change Approved	<table border="1" style="width: 100%; border-collapse: collapse;"> <tr><td style="padding: 2px;">Name:</td></tr> <tr><td style="padding: 2px;">Title:</td></tr> <tr><td style="padding: 2px;">Company:</td></tr> <tr><td style="padding: 2px;">Date:</td></tr> <tr><td style="padding: 2px;">Signature:</td></tr> </table>		Name:	Title:	Company:	Date:	Signature:
Name:							
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## DOCUMENT APPROVAL

Name	Function
Riviera, Antonio	Division Marketing Manager
Naso, Lorenzo	Division Product Manager
Calderoni, Michele	Division Q.A. Manager

**IMS (Industrial & Multisegment Sector)**  
**APM (Analog, Power, MEMS) Group**  
**Voltage Regulator, Interface, Advanced logic & Power RF**  
**Quality & Reliability**

**Rel-6043.013.09W**

Reliability Evaluation Plan and Results on  
**ST3232CDR**  
**BCD3S TECHNOLOGY**

**Line: UW55AA6**

**Package: SO16L**

Test	Conditions	S.S.	Requirement	Results
PRECONDITIONING OF SMD DEVICES BEFORE TC/THB/PP	DRYNG 24H @ 125°C STORE 168h @ TA=85°C RH=85% IR 3 times @ Tmax= 260°C		Parameter deviation within spec. limits after go no go test.	No parameter deviation out of spec. limits at end of preconditioning
H.T.S.	TA=150°C	77x1 Lot	Parameter deviation within spec. limits at 1000h	No parameter deviation out of spec. limits at 1000 hours
T.H.B.	<i>D.U.T. PRECONDITIONED JLI</i> TA=85°C – RH=85% Vbias=+5V +20V -20V	77x1 Lot	Parameter deviation within spec. limits at 1000h	No parameter deviation out of spec. limits at 1000 hours
H.T.B.	TA=125°C – Vbias =+6V +25 -25	77x1 Lot	Parameter deviation within spec. limits at 1000h	No parameter deviation out of spec. limits at 1000 hours
PRESSURE POT	<i>D.U.T. PRECONDITIONED JLI</i> TA=121°C – PA=2ATM	77x1 Lot	Parameter deviation within spec. limits at 168h	No parameter deviation out of spec. limits at 168 hours
THERMAL CYCLES AIR TO AIR	<i>D.U.T. PRECONDITIONED JDI</i> TA=-65°C TO 150°C 1 HOUR/CYCLE	77x1 Lot	Parameter deviation within spec. limits at 500cycles	No parameter deviation out of spec. limits at 500 cycles
SMD MOISTURE INDUCED STRESS	DRYNG 24H @ 125°C STORE 168H @ TA=85°C RH=85% IR 3 times @ Tmax= 260°C	25x1 Lot	Parameter deviation within spec. limits at end of test	No parameter deviation out of spec. limits at end of test

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